FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention

[HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF]

Application Number:

Date:

First Named Applicant: Mr. Sung-Fei Wang

Attorney Docket Number: 10233-US-PA

TOTAL FEE AUTHORIZED \$810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
	·	Subtotal Fo	r Basic Filing Fees: \$ 770

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$		
Total Claims : 20	0	1202	18	0		
Independent Claims : 3	0	1201	86	0		
Subtotal For Extra Claims Fees: \$ 0						

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$	
Recording Each Patent	00000000	1	8021	40	40	
Assignment Per Property Fee						
Subtotal For Additional Fees: \$40						

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Credit account number: 1007

Expiration Date (YYYYMMDD): 2005-12-31

Authorized name: YEH, WEN-HUNG

Billing address: 99999